



Material Content Data Sheet



Sales Product Name		ICE3BR0665JZ		Issued		29. August 2013		
MA#		MA001029930						
Package		PG-DIP-7-3		Weight*		645.54 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.709	0.88	0.88	8843	8843
leadframe	inorganic material	phosphorus	7723-14-0	0.048	0.01		75	
	non noble metal	zinc	7440-66-6	0.194	0.03		300	
	non noble metal	iron	7439-89-6	3.872	0.60		5998	
wire	non noble metal	copper	7440-50-8	157.218	24.35	24.99	243545	249918
	noble metal	gold	7440-57-5	0.421	0.07	0.07	652	652
	encapsulation	organic material	carbon black	1333-86-4	2.339	0.36		3623
encapsulation	plastics	epoxy resin	-	63.152	9.78		97828	
	inorganic material	silicondioxide	60676-86-0	402.302	62.32	72.46	623203	724654
	leadfinish	non noble metal	tin	7440-31-5	6.460	1.00	1.00	10006
plating	noble metal	silver	7440-22-4	1.594	0.25	0.25	2469	2469
glue	plastics	epoxy resin	-	0.391	0.06		605	
	noble metal	silver	7440-22-4	1.842	0.29	0.35	2853	3458
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com